

**/ Descriptions**

TO-277  
TO-277 Plastic package Schottky diode.

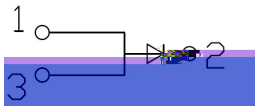
**/ Features**

$V_F(\text{typ})=0.24\text{V}$   
High Forward Surge Capability, Ultra Low Forward Voltage Drop  $V_F(\text{typ})=0.24\text{V}$ , Excellent High Temperature Stability. HF Product.

**/ Applications**

For use in low voltage,high frequency inverters, free wheeling, and polarity protection applications.

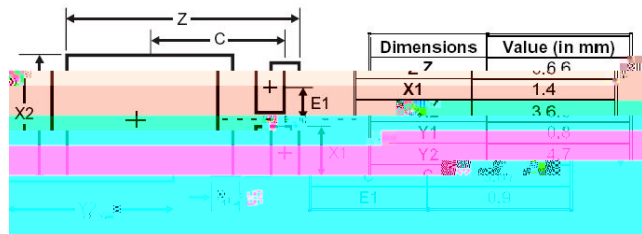
**/ Equivalent Circuit**



**/ Pinning**



PIN1 Anode    PIN 2 Cathode    PIN 3 Anode



Suggested Pad layout

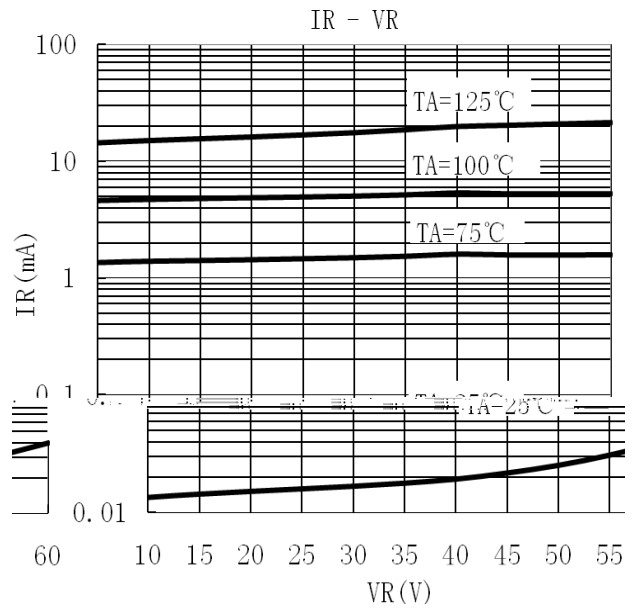
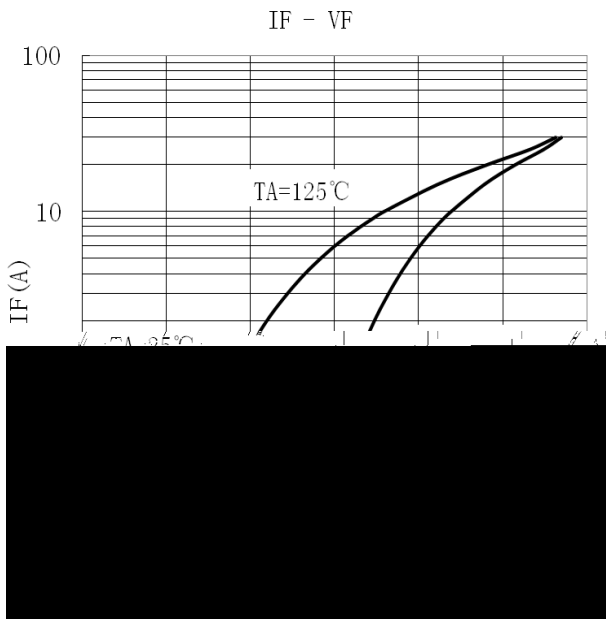
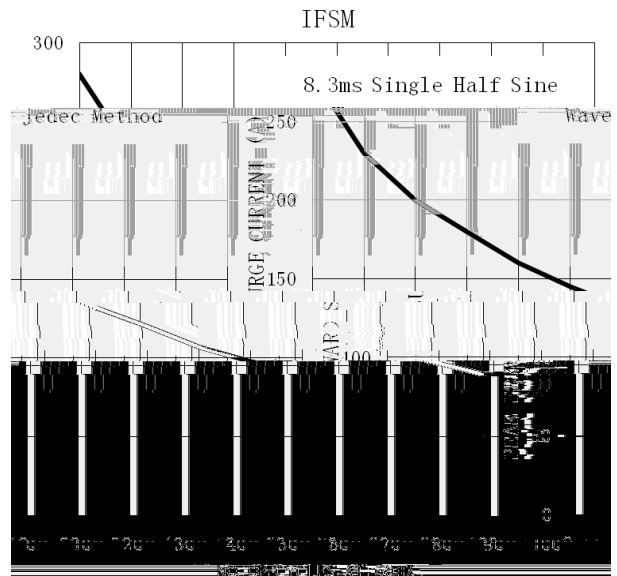
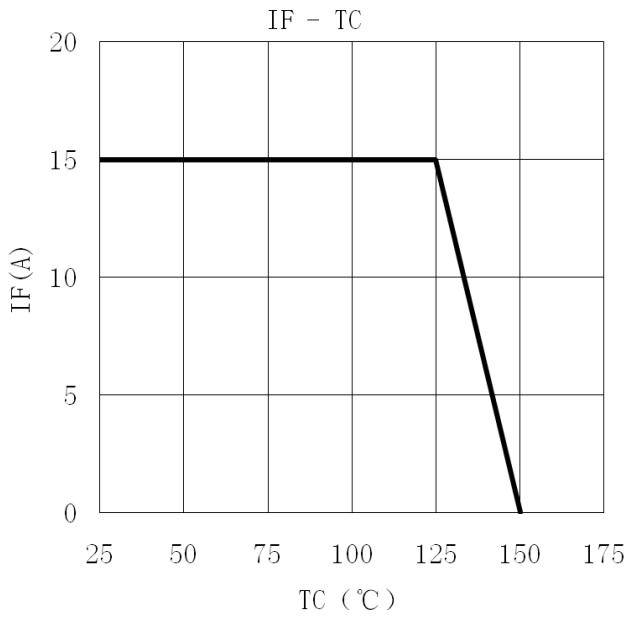
**/ h<sub>FE</sub> Classifications & Marking**

See Marking Instructions.

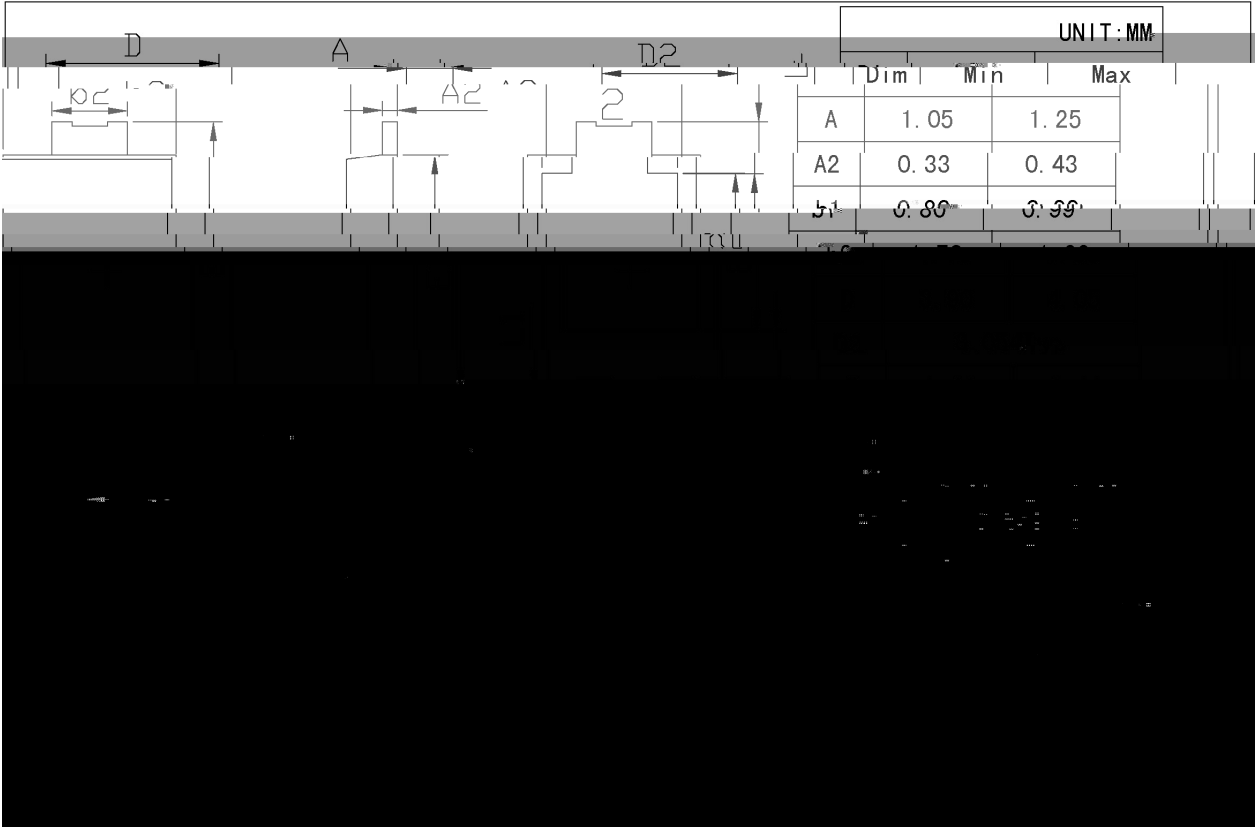
Parameter

Symbol

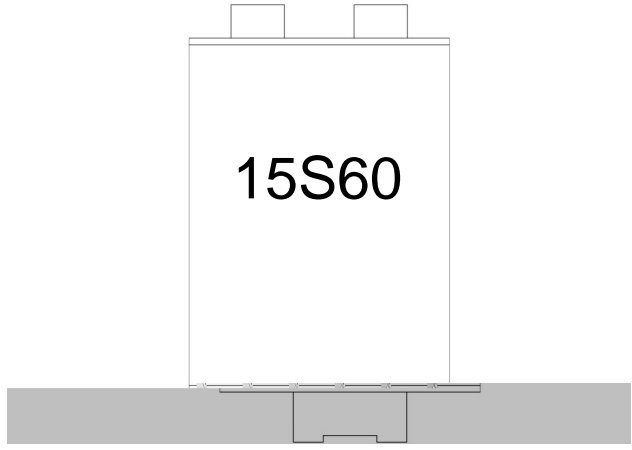
**/ Electrical Characteristic Curve**



**/ Package Dimensions**

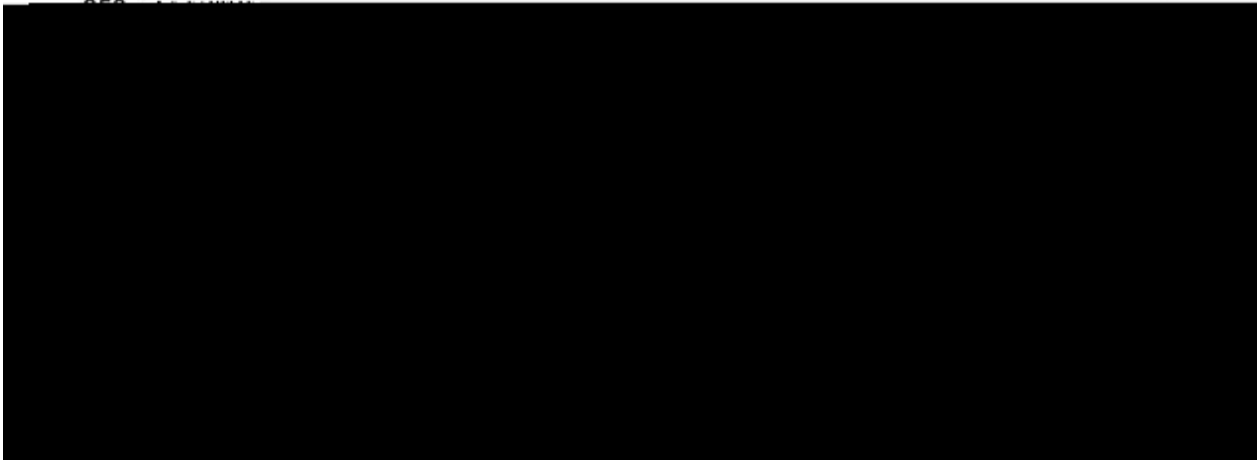


**/ Marking Instructions**



(, J- ' . . . . .  
!!!! . . . . .  
Note:  
(, J- ' Product Type.  
\*\*\*\*: Lot No. Code, code change with Lot No.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



- |   |        |     |            |        |   |                                       |
|---|--------|-----|------------|--------|---|---------------------------------------|
| 1 | 150    | 180 | 60         | 90sec; | Note:                                     | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245..5 |     | 5..0.5sec; |        | 2.Peak Temp.:245..5 , Duration:5..0.5sec. |                                       |
| 3 |        | 2   | 10         | /sec.  | 3. Cooling Speed: 2~10 /sec.              |                                       |

60 ... 5 10...